IN THE CLAIMS:

Claims 9, 10, 12, 14, 18, 20 and 21 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1-8. (canceled)

9. (currently amended) A device for establishing electrical contact with a lead element extending from an IC device, comprising:

a one-piece substrate bounded by a first ~~substantially planar~~ surface and an opposing, second ~~substantially planar~~ surface and having at least one conductive trace, wherein said first surface is configured for mounting a plurality of IC devices thereto;

a spring contact including a base portion and a contact portion, said contact portion comprising a resiliently compressible coil spring comprising a plurality of coils configured to bias against and electrically contact ~~said~~ a lead element of ~~said~~ an IC device of said plurality of IC devices, and said base portion extending generally longitudinal from said contact portion and transversely to the coils of the coil spring; and

an aperture including a seat portion opening onto said first ~~substantially planar~~ surface of said one-piece substrate and a retaining portion having a first end connected to an opposing end of said seat portion and a second end of a smaller lateral extent than the seat portion extending a depth at least partially into said one-piece substrate therefrom, said seat portion of said aperture sized and configured to at least partially contain said contact portion of said spring contact and support the coils of the coil spring during compression thereof, and said retaining portion of said aperture configured to receive and electrically connect said base portion of said spring contact to said at least one conductive trace.

10. (currently amended) The device of claim 9, wherein said second end of said retaining portion does not extend entirely through said one-piece substrate to said opposing, second ~~substantially planar~~ surface.

11. (previously presented) The device of claim 9, further comprising a layer of conductive material disposed on at least a portion of an interior wall of said aperture, said layer of conductive material electrically connecting said base portion of said spring contact to said at least one conductive trace.

12. (currently amended) The device of claim 11, wherein said at least one conductive trace is formed on said first ~~substantially planar~~ surface of said one-piece substrate.

13. (previously presented) The device of claim 11, wherein said at least one conductive trace is formed on an intermediate plane within said one-piece substrate.

14. (currently amended) The device of claim 11, wherein said retaining portion of said aperture extends through said one-piece substrate and opens onto said opposing, second ~~substantially planar~~ surface of said one-piece substrate and said at least one conductive trace is formed on said opposing, second ~~substantially planar~~ surface of said one-piece substrate.

15. (previously presented) The device of claim 9, further comprising a volume of conductive filler material disposed in and filling at least a partial depth of said aperture and electrically contacting said base portion of said spring contact.

16. (previously presented) The device of claim 15, wherein said conductive filler material is electrically connected to said at least one conductive trace of said one-piece substrate.

17. (previously presented) The device of claim 16, wherein said at least one conductive trace is formed on an intermediate plane within said one-piece substrate.

18. (currently amended) The device of claim 16, wherein said retaining portion of said aperture extends through said one-piece substrate and opens onto said opposing, second ~~substantially planar~~ surface of said one-piece substrate and said at least one conductive trace is formed on said opposing, second ~~substantially planar~~ surface of said one-piece substrate.

19. (canceled)

20. (currently amended) The device of claim 9, wherein said second end of said retaining portion opens onto said opposing, second ~~substantially planar~~ surface of said one-piece substrate.

21. (currently amended) The device of claim 9, wherein said seat portion comprises a generally hemispherical recess formed in said first ~~substantially planar~~ surface of said one-piece substrate, a generally conical recess formed in said first ~~substantially planar~~ surface of said one-piece substrate, or a generally cylindrical recess formed in said first ~~substantially planar~~ surface of said one-piece substrate.

22. (previously presented) The device of claim 9, wherein said seat portion is further configured to at least partially align said lead element of said IC device relative to said spring contact.

23. (previously presented) The device of claim 9, wherein said contact portion of said spring contact comprises a resiliently compressible coil spring having at least two spring coils for contacting portions thereof and configured to bias against and electrically contact said lead element of said IC device.

24-41. (canceled)

42. (withdrawn) The device of claim 9, wherein said resiliently compressible coil spring of said contact portion further comprises at least one point for penetrating an outer surface of said lead element of said IC device.

43. (withdrawn) The device of claim 9, wherein said resiliently compressible coil spring of said contact portion further comprises a contact element selected from the group consisting of a sharp edge formed by a cross-section of said resiliently compressible coil spring, a blade extending longitudinally along a surface of said resiliently compressible coil spring, a blade extending circumferentially around a surface of said resiliently compressible coil spring or a barb protruding from a surface of said resiliently compressible coil spring.

44. (withdrawn) The device of claim 9, further comprising a clamping element configured to secure said IC device to said first substantially planar surface of said substantially planar substrate.

45. (withdrawn) The device of claim 44, wherein said clamping element comprises a stab-in-place clip.